Specification of Thermoelectric Module

TEHC1-19940

Description

The 199 couples, 62 mm × 62 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74℃ or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
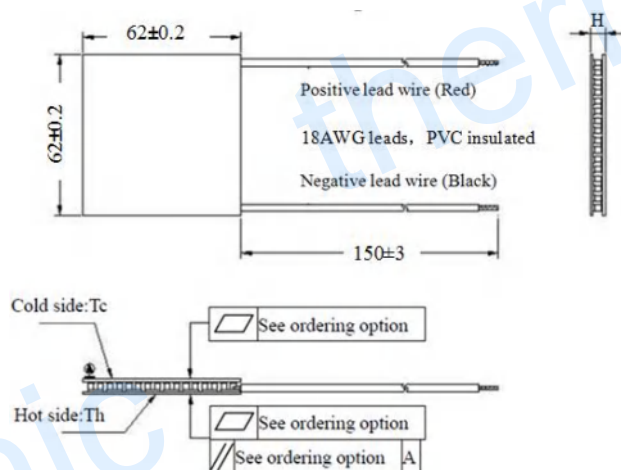- Exceptionally reliable in quality, high performance

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (ºC)	27	50	Hot side temperature at environment: dry air, N_2
DT_{max} (ºC)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U_{max} (Voltage)	26.2	28.2	Voltage applied to the module at DT_{max}
I_{max} (Amps)	40	40	DC current through the modules at DT_{max}
Q_{Cmax} (Watts)	669.4	730.0	Cooling capacity at cold side of the module under DT=0 ºC
AC resistance (Ohms)	0.49	0.52	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters

62±0.2
62±0.2
Positive lead wire (Red)
18AWG leads, PVC insulated
Negative lead wire (Black)
150±3
H

Cold side:Tc
See ordering option
Hot side:Th
See ordering option
See ordering option   A

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138ºC)

2. T200: CuAgSn (Tmelt = 217°C)

3. T240: SbSn (Tmelt = 240°C)

C. Ceramics:

1. Alumina (Al_2O_3, white 96%)

2. Aluminum Nitride (AlN)

B. Sealant:

1. NS: No sealing (Standard)

2. SS: Silicone sealant

3. EPS: Epoxy sealant
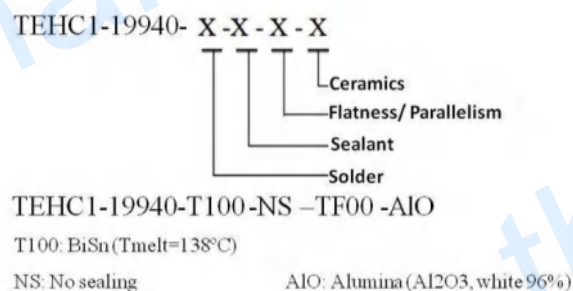
D. Ceramics Surface Options:

1. Blank ceramics (not metalized)

2. Metalized

Ordering Option

Suffix	Thickness / H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.8±0.1	0:0.12/0.12	150±3/Specify
TF	1:3.8±0.05	1:0.06/0.06	150±3/Specify
Eg. TF00: Thickness 3.8±0.1(mm) and Flatness 0.12/0.12(mm)			

Naming for the Module

TEHC1-19940- X -X - X - X

Ceramics
Flatness/ Parallelism
Sealant
Solder

TEHC1-19940-T100-NS –TF00 -AlO

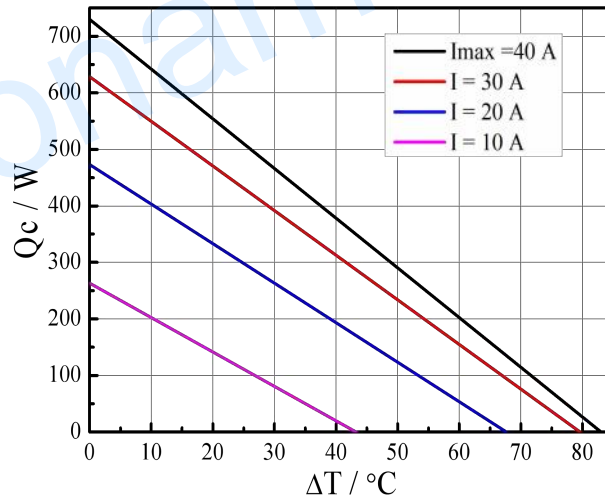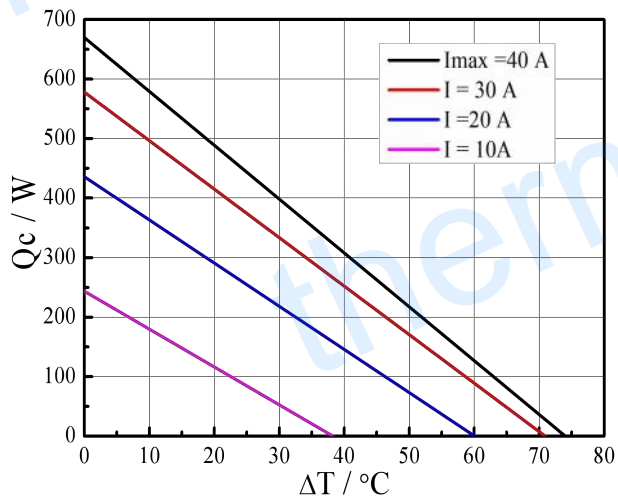T100: BiSn (Tmelt=138°C)

NS: No sealing

AlO: Alumina (Al2O3, white 96%)

Specification of Thermoelectric Module

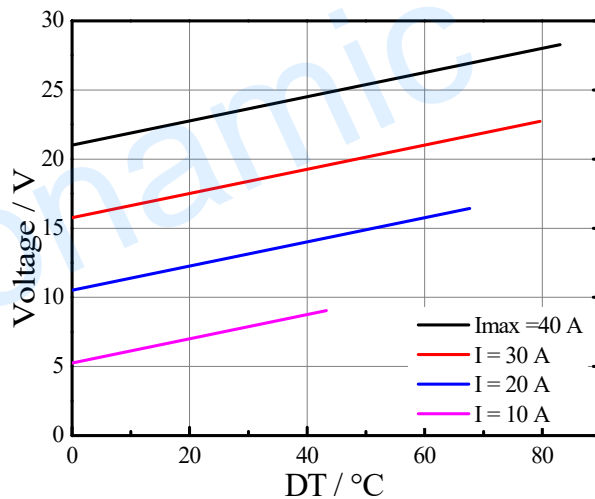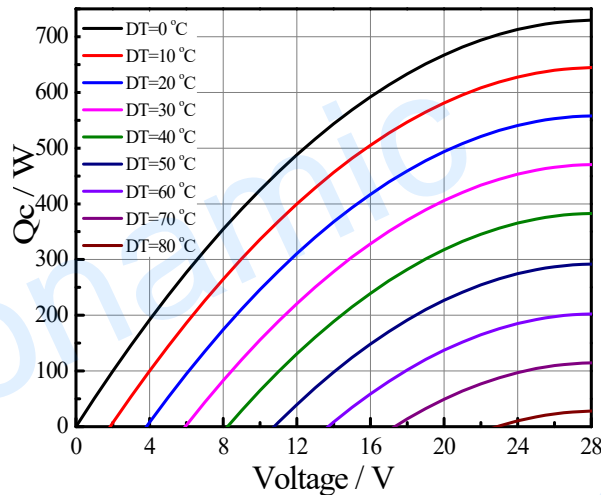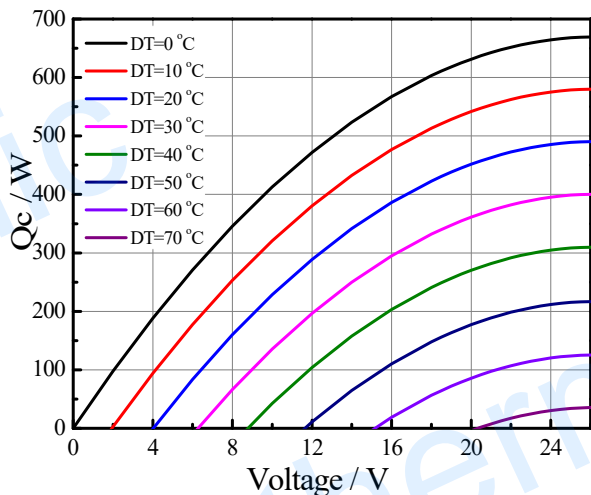## TEHC1-19940

Performance Curves at Th=27 ºC

Performance Curves at Th=50 ºC

Standard Performance Graph Qc= f(DT)
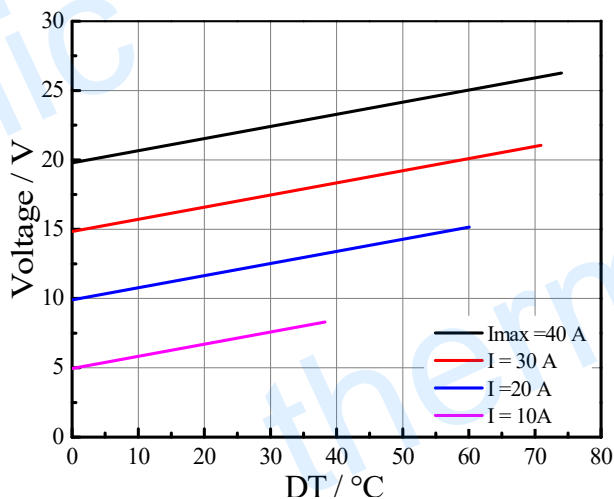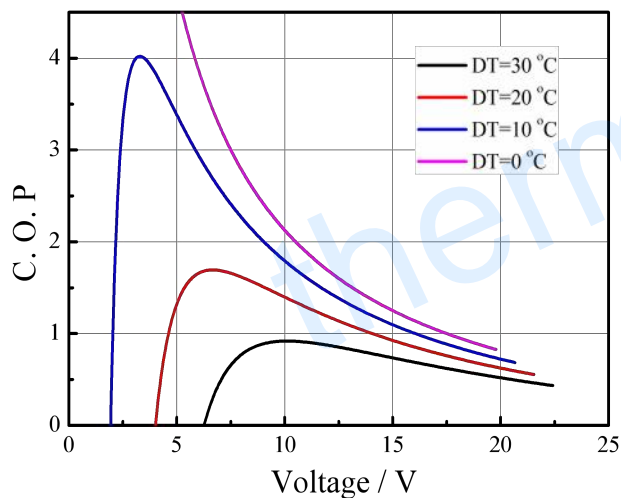

Standard Performance Graph V= f(DT)
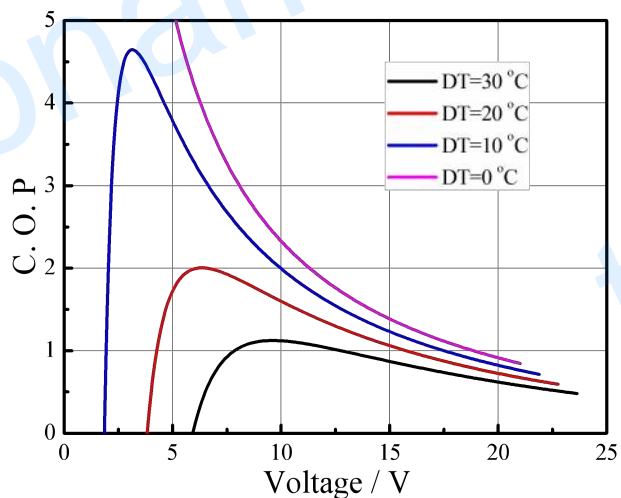

Standard Performance Graph Qc= f(V)

Specification of Thermoelectric Module
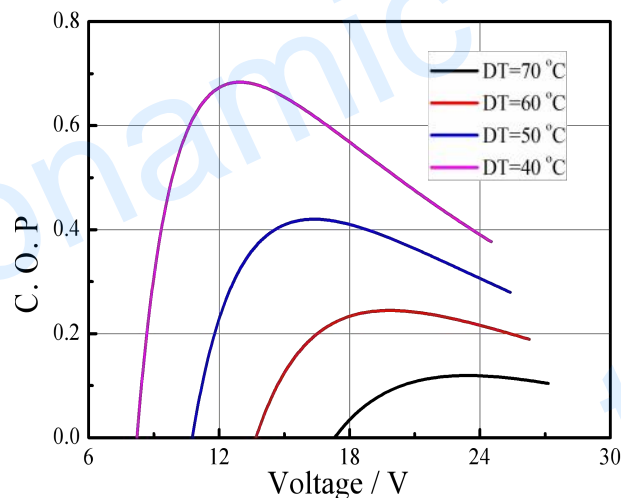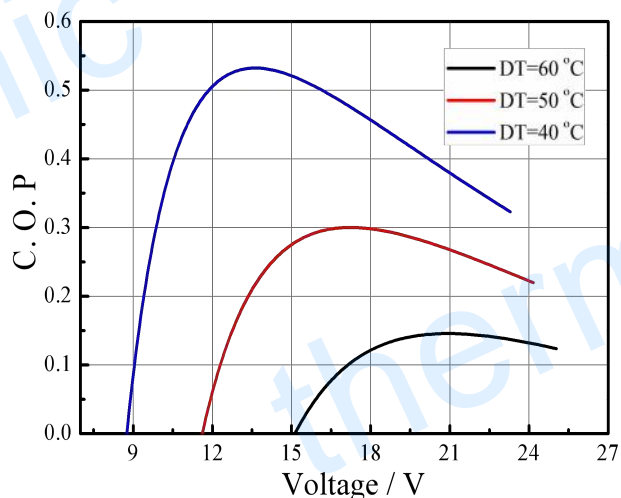
TEHC1-19940

Performance Curves at Th=27 ºC

Performance Curves at Th=50 ºC

Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 ˚C

Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 ˚C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

● Attach the cold side of module to the object to be cooled

● Attach the hot side of module to a heat radiator for heat dissipating

● Operation below I_{max} or V_{max}

● Work under DC